



**SDI Review Form 1.6**

Journal Name:	<a href="#">Journal of Engineering Research and Reports</a>
Manuscript Number:	Ms_JERR_65046
Title of the Manuscript:	Die Crack Resolution Through Pick-up Process Optimization for BGA Package
Type of the Article	Original Research Article

**General guideline for Peer Review process:**

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/journal/10/editorial-policy> )

**PART 1: Review Comments**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Compulsory</b> REVISION comments	<p>The paper presents an interesting piece of research, with also very interesting results. However before publication some improvements are needed:</p> <ul style="list-style-type: none"> <li>- The paper can be perfectly understood. However some sentences present a low standard of scientific English. A review is needed by a specialist in scientific English</li> <li>- The scientific and technical content must be explained more in detail. The only qualitative explanation is Figure 5 and the previous paragraph.</li> <li>- The state of the art must be detailed. The existing state of the art in the paper is limited to 3 sentences, and the last one is placed in the Conclusions section: "With the new and continuous technology trends and breakthroughs, challenges in assembly manufacturing are unavoidable [1-4]. Highlighted is the process where the issue was encountered. important to note that assembly process flow varies with the product and the technology [5-7]. Studies and learnings shared in [8-10] are helpful in reinforcing robustness and optimization of assembly processes particular at die attach process.". Please, explain the content of the knowledge in the field, based on the references, and the contribution of your research beyond such state of the art.</li> </ul> <p>I am sure that attending these suggestions a good paper can be obtained.</p>	
<b>Minor</b> REVISION comments		
<b>Optional/General</b> comments		



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**PART 2:**

	<b>Reviewer's comment</b>	<b>Author's comment</b> (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Are there ethical issues in this manuscript?</b>	<i>(If yes, Kindly please write down the ethical issues here in details)</i>	

**Reviewer Details:**

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